

Semiconductor devices — Mechanical and climatic test methods —

Part 8: Sealing

The European Standard EN 60749-8:2003 has the status of a British Standard

ICS 31.080.01

National foreword

This British Standard is the official English language version of EN 60749-8:2003. It is identical with IEC 60749-8:2002. It partially supersedes BS EN 60749:1999 which will be withdrawn on 2005-10-01.

The UK participation in its preparation was entrusted to Technical Committee EPL/47, Semiconductors, which has the responsibility to:

- aid enquirers to understand the text;
- present to the responsible international/European committee any enquiries on the interpretation, or proposals for change, and keep the UK interests informed;
- monitor related international and European developments and promulgate them in the UK.

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Cross-references

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Summary of pages

This document comprises a front cover, an inside front cover, the EN title page, pages 2 to 16, an inside back cover and a back cover.

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English version

**Semiconductor devices -
Mechanical and climatic test methods
Part 8: Sealing**
(IEC 60749-8:2002 + corrigendum 2003)

Dispositifs à semiconducteurs -
Méthodes d'essais mécaniques
et climatiques
Partie 8: Etanchéité
(CEI 60749-8:2002 + corrigendum 2003)

Halbleiterbauelemente -
Mechanische und klimatische Prüfverfahren
Teil 8: Dichtheit
(IEC 60749-8:2002 + Corrigendum 2003)

This European Standard was approved by CENELEC on 2002-09-24. CENELEC members are bound to comply with the CEN/CENELEC Internal Regulations which stipulate the conditions for giving this European Standard the status of a national standard without any alteration.

Up-to-date lists and bibliographical references concerning such national standards may be obtained on application to the Central Secretariat or to any CENELEC member.

This European Standard exists in three official versions (English, French, German). A version in any other language made by translation under the responsibility of a CENELEC member into its own language and notified to the Central Secretariat has the same status as the official versions.

CENELEC members are the national electrotechnical committees of Austria, Belgium, Czech Republic, Denmark, Finland, France, Germany, Greece, Hungary, Iceland, Ireland, Italy, Luxembourg, Malta, Netherlands, Norway, Portugal, Slovakia, Spain, Sweden, Switzerland and United Kingdom.

CENELEC

European Committee for Electrotechnical Standardization
Comité Européen de Normalisation Electrotechnique
Europäisches Komitee für Elektrotechnische Normung

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Foreword

The text of the International Standard IEC 60749-8:2002 was approved by CENELEC as EN 60749-8 on 2002-09-24.

The text of this International Standard was reproduced from IEC 60749:1996, chapter 3, clause 5 without change. Therefore, it has not been submitted to vote a second time and is still based on document 47/1574/FDIS.

The following dates were fixed:

- latest date by which the EN has to be implemented
at national level by publication of an identical
national standard or by endorsement (dop) 2004-01-01
- latest date by which the national standards conflicting
with the EN have to be withdrawn (dow) 2005-10-01

Each test method governed by this standard and which is part of the series is a stand-alone document, numbered EN 60749-2, EN 60749-3, etc. The numbering of these test methods is sequential, and there is no relationship between the number and the test method (i.e. no grouping of test methods). The list of these tests will be available in the CENELEC internet site and in the catalogue.

Updating of any of the individual test methods is independent of any other part.

Annexes designated "normative" are part of the body of the standard.
In this standard, annex ZA is normative.
Annex ZA has been added by CENELEC.

Endorsement notice

The text of the International Standard IEC 60749-8:2002 and its corrigendum April 2003 was approved by CENELEC as a European Standard without any modification.

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INTRODUCTION

Activity within IEC technical committee 47, working group 2, includes the generation, coordination and review of climatic, electrical (of which only ESD, latch-up and electrical conditions for life tests are considered), mechanical test methods, and associated inspection techniques needed to assess the quality and reliability of the design and manufacture of semiconductor products and processes.